

APKF3030SEXXC/E HYPER ORANGE

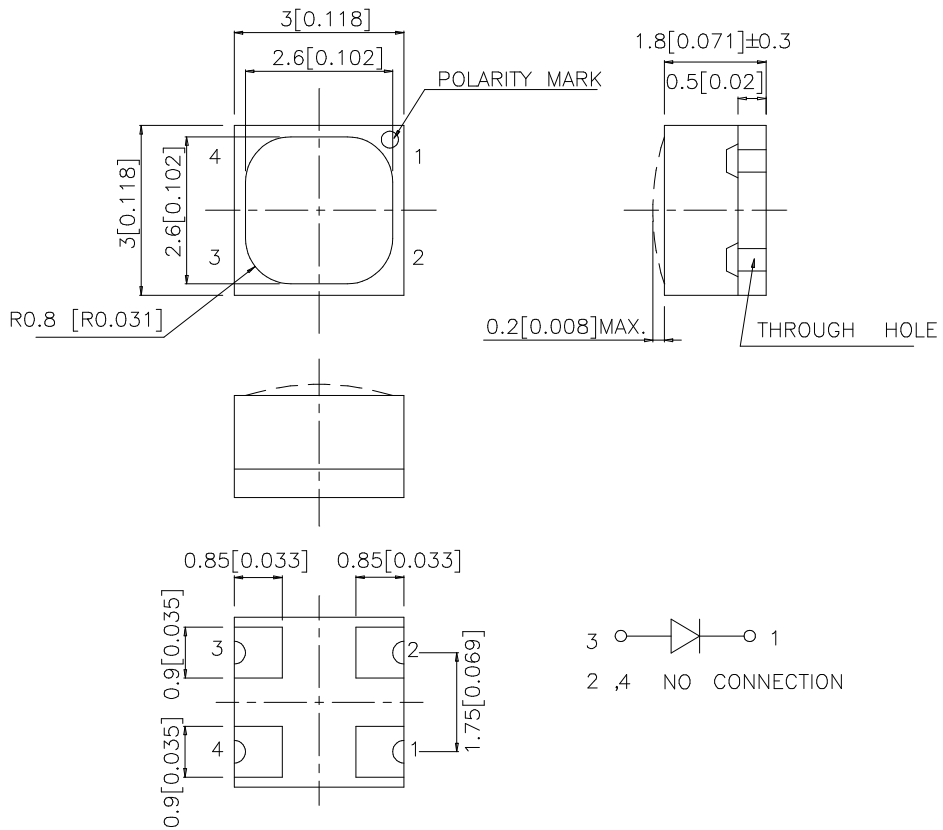
Features

- LOW POWER CONSUMPTION.
- 3.0mmx3.0mm SMT LED, 2.0mm(MAX.) THICKNESS.
- ONE ORANGE CHIP IN ONE PACKAGE.
- CAN PRODUCE ANY COLOR IN VISIBLE SPECTRUM, INCLUDING WHITE LIGHT.
- PACKAGE : 1000PCS / REEL.

Description

The Hyper Orange source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	2θ1/2
APKF3030SEXXC/E	HYPER ORANGE (InGaAlP)	WATER CLEAR	180	400	100°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at T_A=25°C

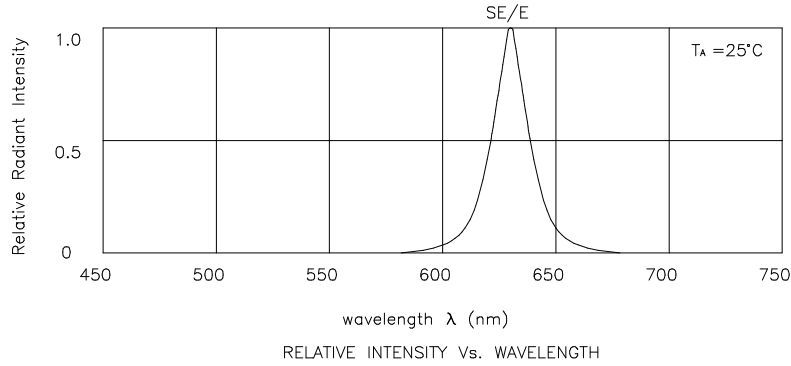
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Hyper Orange	630		nm	I _F =20mA
λ _D	Dominate Wavelength	Hyper Orange	621		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Hyper Orange	20		nm	I _F =20mA
C	Capacitance	Hyper Orange	25		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Hyper Orange	2.0	2.5	V	I _F =20mA
I _R	Reverse Current	Hyper Orange		10	μA	V _R = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Hyper Orange	Units
Power dissipation	150	mW
DC Forward Current	30	mA
Peak Forward Current [1]	195	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

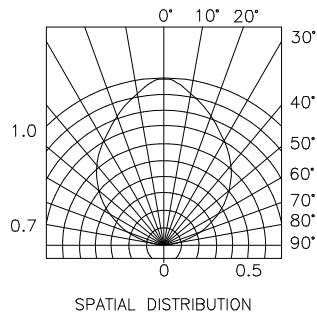
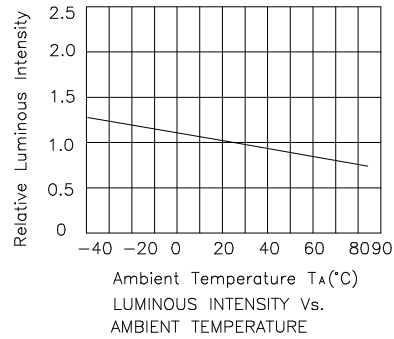
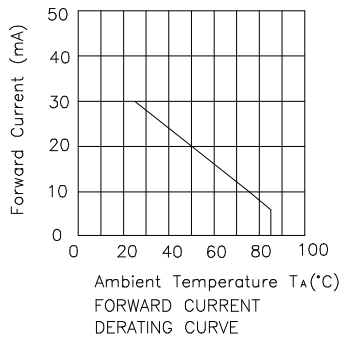
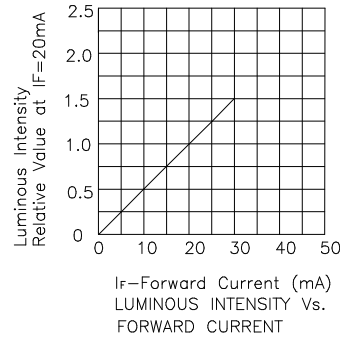
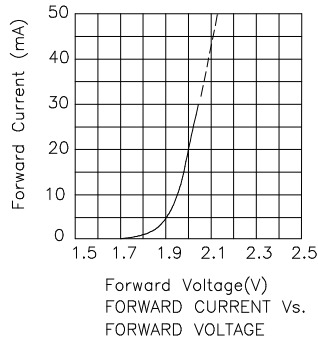
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



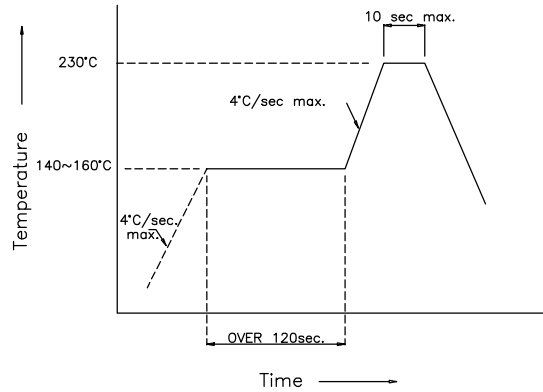
Hyper Orange

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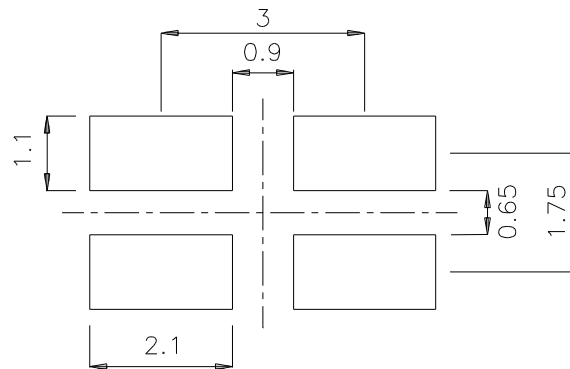


APKF3030SEXXC/E SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

